

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Zhen Ding Technology Co., Ltd.	01/01/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	GARUDA TECHNOLOGY CO., LTD
<b>Street Address:</b>	4F., NO.156, SEC 1, ZHONGSHAN RD., BANQIAO DIST., NEW TAIPEI CITY 22065, TAIWAN(R.O.C)
<b>City:</b>	New Taipei
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Patent Number:</b>	7698811
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<b>SIGNATURE:</b>	/Zhigang Ma/
<b>DATE SIGNED:</b>	01/17/2017
<b>Total Attachments: 3</b>	
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**ASSIGNMENT OF PATENT**

Atty Dkt No.:

WHEREAS, ZHEN DING TECHNOLOGY CO., LTD. of NO. 6, LANE 28, SAN HO RD., SAN SHI VILLAGE, TAYUAN, TAOYUAN, TAIWAN, is the owner of the entire right, title and interest of the U.S. Patents and Patent Applications listed in Exhibit A.

WHEREAS, GARUDA TECHNOLOGY CO., LTD., hereinafter referred to as "assignee" whose mailing address is 4F., NO.156 • SEC.1 • ZHONGSHAN RD., BANQIAO DIST., NEW TAIPEI CITY 22065, TAIWAN, is desirous of acquiring the entire right, title and interest in the same;

NOW, THEREFORE, for good and valuable consideration, the receipt whereof is acknowledged, we, the patent and patent applications owners, by these presents do sell, assign and transfer unto said assignee the entire right, title and interest in and to the aforementioned Patents and Patent Applications; the same to be held and enjoyed by the said assignee for his own use and behoof, and for his legal representatives and assigns, to the full end of the term for which said Patents is granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this assignment day of Jan 1st, 2017, at Shenzhen, Guangdong, China

**ZHEN DING TECHNOLOGY CO., LTD.**

By: SHEN CHANG-FANG  
Name: SHEN, CHANG-FANG  
Title: Chairman

Exhibit A

28 U.S. Patents and Patent Applications in total:

	Application No.	Patent No.	Title
1	11/309852	7488428	METHOD FOR FORMING STACKED VIA-HOLES IN PRINTED CIRCUIT BOARDS
2	11/560787	7418780	METHOD FOR FORMING STACKED VIA-HOLES IN A MULTILAYER PRINTED CIRCUIT BOARD
3	11/614362	8377252	APPARATUS FOR SPRAYING ETCHANT ONTO PRINTED CIRCUIT BOARD
4	11/865619	7897055	METHOD FOR MANUFACTURING MULTILAYER FLEXIBLE PRINTED CIRCUIT BOARD
5	11/940910	7854197	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARDS USING LEGEND PRINTING STENCIL
6	11/959194	8001684	METHOD FOR MANUFACTURING FLEXIBLE PRINTED CIRCUIT BOARDS
7	11/959212	7698811	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARDS USING INNER SUBSTRATE
8	11/960659	7989048	FLEXIBLE BASE FOR MANUFACTURING FLEXIBLE PRINTED CIRCUIT BOARDS
9	11/967004	7877872	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD
10	11/967006	8332984	CLEANING APPARATUS
11	12/057654	8089003	PRINTED CIRCUIT BOARD ASSEMBLY
12	12/109223	7897199	METHOD FOR PLATING FLEXIBLE PRINTED CIRCUIT BOARD
13	12/110542	8088294	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARDS
14	12/135842	8101266	MULTILAYER PRINTED CIRCUIT BOARD
15	12/135849	8164000	FLEXIBLE PRINTED CIRCUIT BOARDS INCLUDING CARBON NANOTUBE BUNDLES
16	12/144260	7985482	STIFFENER SHEET AND FLEXIBLE PRINTED CIRCUIT BOARD USING THE SAME
17	12/332321	8268537	METHOD FOR MANUFACTURING PRINTED CIRCUIT BOARD
18	12/346804	7839647	INSULATING FILM, PRINTED CIRCUIT BOARD SUBSTRATE AND PRINTED CIRCUIT BOARD INCLUDING SAME

19	12/535909	8062580	APPARATUS FOR RECYCLING METAL FROM METAL IONS CONTAINING WASTE SOLUTION
20	12/979369	8251712	PRINTED CIRCUIT BOARD MODULE
21	13/046792	8580068	METHOD FOR MANUFACTURING RIGID-FLEXIBLE PRINTED CIRCUIT BOARD
22	13/049906	8735728	PRINTED CIRCUIT BOARD WITH FINS
23	13/108991	8997343	METHOD FOR MANUFACTURING MULTILAYER PRINTED CIRCUIT BOARD
24	13/233189	8723050	MULTILAYER PRINTED CIRCUIT BOARD AND METHOD FOR MAKING SAME
25	13/308560	8567468	APPARATUS AND METHOD FOR PRESSING PRINTED CIRCUIT BOARD
26	13/757857	8647518	RESIN COATED COPPER FOIL, METHOD FOR MANUFACTURING SAME AND MULTI-LAYER CIRCUIT BOARD
27	14/512556	\	RIGID-FLEXIBLE PRINTED CIRCUIT BOARD,METHOD FOR MANUFACTURING SAME,AND PRINTED CIRCUIT BOARD MODULE
28	13/161502	8500949	APPARATUS AND METHOD FOR WET PROCESSING SUBSTRATE